

APPLICATION DATA SHEET

INVENTOR INFORMATION

Inventor one given name:	Kiyoshi
Family name:	DEMIZU
Postal address line one:	c/o Shin-Etsu Handotai Co., Ltd.
Postal address line two:	4-2, Marunouchi 1-chome,
City:	Tokyo
State or Province:	JAPAN
Country:	100-0005
Postal or Zip Code:	Tokyo
City of residence:	JAPAN
Country of residence:	JAPAN
Citizenship Country:	
Inventor two given name:	Tadahiro
Family name:	KATO
Postal address line one:	c/o Shin-Etsu Handotai Co., Ltd.
Postal address line two:	Shirakawa R&D Center 150, Aza Ohira,
Postal address line three:	Oaza Odakura, Nishigo-mura,
Postal address line four:	Nishishirakawa-gun
City:	Fukushima
State or Province:	JAPAN
Country:	961-8061
Postal or Zip Code:	Fukushima
City of residence:	JAPAN
Country of residence:	JAPAN
Citizenship Country:	
Inventor three given name:	Shigeyoshi
Family name:	NETSU
Postal address line one:	c/o Shin-Etsu Handotai Co., Ltd.
Postal address line two:	Shirakawa R&D Center 150, Aza Ohira,
Postal address line three:	Oaza Odakura, Nishigo-mura,
Postal address line four:	Nishishirakawa-gun
City:	Fukushima
State or Province:	JAPAN
Country:	961-8061
Postal or Zip Code:	Fukushima
City of residence:	JAPAN
Country of residence:	JAPAN
Citizenship Country:	

CORRESPONDENCE INFORMATION

Correspondence customer number: 23911

APPLICATION INFORMATION

Title line one: SEMICONDUCTOR WAFER AND
Title line two: APPARATUS OF PROCESS FOR
Title line three: FABRICATING SEMICONDUCTOR
Title line four: DEVICES
Total drawing sheets: 11
Formal drawings?: Yes
Application type: Utility
Docket Number: 155/50674

REPRESENTATIVE INFORMATION

Representative customer number: 23911

CONTINUITY INFORMATION

This application is a: 371 of
Application one: PCT/JP01/03635
Filing date: April 26, 2001
Patent number:

PRIOR FOREIGN APPLICATIONS

Foreign application one: 2000-128502
Filing date: April 27, 2000
Country: Japan
Priority claimed: Yes